



BGA / LGA / QFN / QFP Test Contact Probe (Unit : mm)

Applications

- BGA / LGA / QFN / QFP package function test.
- BGA / LGA / QFN / QFP package burn-in test.

Features

- Superior high frequency performance matches with high speed testing.
- High performance, high durability and high reliability short spring probe.
- In-house micron technology can realize stable contact resistance.

Specifications

Pitch	0.3mm~1.27mm
Probe Length	5.7mm~2.2mm (Operating Length 5.05mm~1.8mm)
Operating Temperature	-55°C~+125°C(+150°C) ※

※ Customized for 150°C case